

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Ralf Otremba	04/26/2007
Josef Hoeglauer	04/26/2007
Stefan Landau	04/26/2007
Erwin Huber	04/26/2007
RECEIVING PARTY DATA	
Name:	Infineon Technologies AG
Street Address:	St.-Martin-Strasse 53
City:	Muenchen
State/Country:	GERMANY
Postal Code:	81669
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11733679
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ATTORNEY DOCKET NUMBER:	2006 P 54632 US (INF-LL)
NAME OF SUBMITTER:	Julie Russell

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**PATENT
REEL: 019495 FRAME: 0542**

Total Attachments: 2

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ASSIGNMENT

For good and valuable consideration, I, **Ralf Otremba**, residing at Ahornstrasse 42, 87600 Kaufbeuren, Germany, a citizen of Germany; **Josef Hoeglauer**, residing at Aberlestr. 13A, 81371 Muenchen, Germany, a citizen of Germany; **Stefan Landau**, residing at Danzinger Str. 11, 61273 Wehrheim, Germany, a citizen of Germany; **Erwin Huber**, residing at Aberlestr. 12, 81371 Muenchen, Germany, a citizen of Germany

hereby sell, assign, and transfer to **Infineon Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Strasse 53, Muenchen, 81669, Germany;

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewithin, and is entitled:

Multi-Chip Module

and in and to said application and all divisional, continuing substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths,

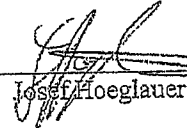
assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: 26.04.2007


Ralf Otremba

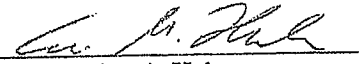
Date: April- 26 - 2007


Josef Hoeglauer

Date: 26.04.07


Stefan Landau

Date: 26.04.07


Erwin Huber